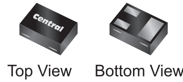
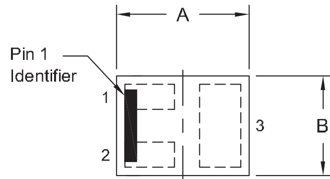
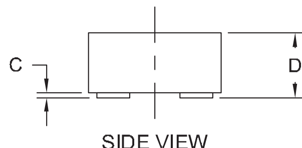
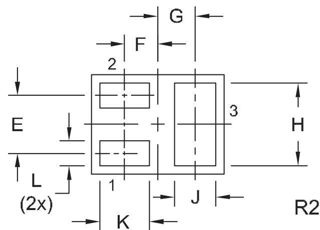
Package Details
TLM3D6D8 Case



Mechanical Drawing







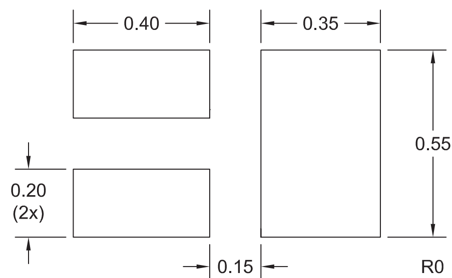
DIMENSIONS				
	INCHES		MILLIMETERS	
SYMBOL	MIN	MAX	MIN	MAX
A	0.029	0.034	0.75	0.85
B	0.021	0.026	0.55	0.65
C	0.000	0.002	0.00	0.05
D	0.012	0.016	0.31	0.40
E	0.014		0.35	
F	0.008		0.20	
G	0.009		0.225	
H	0.017	0.022	0.45	0.55
J	0.008	0.012	0.20	0.30
K	0.010	0.014	0.25	0.35
L	0.004	0.008	0.10	0.20

TLM3D6D8 (REV: R2)

Part Marking:
Single Character Alpha/Numeric Code

Lead Code:
Reference individual device data sheet.

Mounting Pad Geometry (Dimensions in mm)

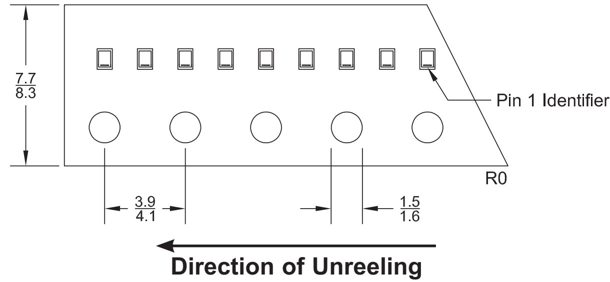


R0 (4-October 2012)

Package Details
TLM3D6D8 Case

Tape Dimensions and Orientation (Dimensions in mm)

Tape Width: 8mm



Devices are taped in accordance with Electronic Industries Association Standard EIA-481-D

Packaging Base

7” Reel = 10,000 pcs.

Reel Labeling Information

Each reel is labeled with the following information:
Central Part Number, Customer Part Number, Purchase Order Number, Quantity, Lot Number, Date Code, Ship Date and Marking Code.

Reel Packing Information

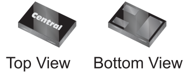
Reel Size	Reels per Box (Maximum)	Parts per Box (Maximum)	Box Dimensions		Shipping Weight (Max.)	
			INCH	CM	LB	KG
7”	9	90,000	9x9x5	23x23x13	3	2
	18	180,000	9x9x9	23x23x23	6	3
	40	400,000	21x9x9	53x23x23	13	6
	108	1,080,000	27x9x17	69x23x43	34	34

Ordering Information

- For devices taped and reeled on 7” reels, add TR suffix to part number.
- All SMDs are available in small quantities for prototype and manual placement applications.

Material Composition Specification

TLM3D6D8 Case



Device average mass . . . . **625 µg**

Fluctuation margin . . . . **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(µg)			(%wt)	(µg)	(ppm)
active device	doped Si	2.88%	18	Si	7440-21-3	2.88%	18	28,800
bond wire	gold	1.6%	10	Au	7440-57-5	1.60%	10	16,000
leadframe	Cu alloy	45.72%	285.75	Cu	7440-50-8	43.52%	272	435,200
				Ni	7440-02-0	1.60%	10	16,000
				Si	7440-21-3	0.32%	2.0	3,200
				Zn	7440-66-6	0.14%	0.9	1,440
				Ag	7440-22-4	0.14%	0.85	1,360
die attach	silver epoxy	0.32%	2.0	Ag	7440-22-4	0.24%	1.5	2,400
				epoxy resin	Proprietary	0.08%	0.5	800
encapsulation*	EMC GREEN	48.96%	306	silica (fused)	60676-86-0	45.92%	287	459,200
				epoxy resin	29690-82-2	1.44%	9.0	14,400
				phenol resin	9003-35-4	1.44%	9.0	14,400
				carbon black	1333-86-4	0.16%	1.0	1,600
plating	Ni/Pd/Au	0.52%	3.25	Ni	7440-02-0	0.47%	2.95	4,720
				Pd	7440-05-3	0.04%	0.25	400
				Au	7440-57-5	0.01%	0.05	80

*EMC GREEN molding compound is Halogen-Free.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.